

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (currently amended): A compound material ~~at least comprises comprising;~~  
a first high heat conductive layer, adapted to conduct thermal capacities from a  
correspondent electronic device; and  
a first electromagnetic interference (EMI) shielding layer, shielding electromagnetic  
interferences from outside of the correspondent electronic device, which is superposed to the first  
high heat conductive layer;  
a second high heat conductive layer, adapted to conduct thermal capacities from a  
correspondent electronic device, which is superposed to the first EMI layer opposite to the first  
high heat conductive layer; and  
a second EMI shielding layer, shielding electromagnetic interferences from outside of the  
correspondent electronic device, which is superposed to the second high heat conductive layer  
opposite to the first EMI shielding layer;  
wherein the first and second EMI shielding layers both comprise a heat conductive sub-  
layer and a plurality of EMI shielding blocks therein, the EMI blocks of the first and second EMI  
shielding layers being separately and alternately arranged in the corresponding heat conductive  
sub-layers and staggered from the corresponding EMI shielding blocks in an overlapped or  
vertical direction thereof.

~~which are integrated together, among which the first EMI shielding layer forms a plurality of pre-set comparted portions.~~

2. (canceled).

3. (currently amended): The compound material as claimed in claim ~~2~~1, wherein the arrangement of the ~~comparted portions~~ EMI shielding blocks of the first and second EMI shielding ~~layer~~ layers is tessellated.

4. (currently amended): The compound material as claimed in claim 3, wherein the ~~comparted portions are a plurality of~~ EMI shielding blocks are formed by filling EMI shielding material into correspondent slots in ~~a~~ the corresponding high heat conductive ~~sub-layer sub-~~ layers of the ~~first-corresponding~~ EMI shielding ~~layer~~ layers.

5. (canceled).

6. (currently amended): The compound material as claimed in claim ~~5~~3, wherein the EMI shielding blocks are made from an electromagnetic wave absorbing material.

7. (currently amended): The compound material as claimed in claim 6, wherein the EMI shielding blocks are integrated with the corresponding heat conductive sub-layer-sub-layers by planography printing or insert-molding methods.

8. - 10. (canceled).

11. (currently amended): The compound material as claimed in claim ~~10~~ 7, wherein the compound material ~~further~~ comprises a third high heat conductive layer which is overlapped on the second EMI shielding layer and opposite to the second heat conductive layer.

12. (currently amended): A compound material at least ~~comprises~~ comprising a pair of overlapped first high heat conductive layer and first electromagnetic interference (EMI) shielding layer, the first EMI shielding layer ~~including~~ comprising a first high heat conductive sub-layer and a first plurality of EMI shielding blocks thereby forming an EMI shielding net and a heat conducting track with the cooperation of the overlapped first heat conductive layer ~~in the meantime~~ and first EMI shielding layer.

13. (currently amended): The compound material as claimed in claim 12, wherein the first heat conductive sub-layer has a plurality of first slots therein and ~~a suitable~~ an EMI shielding material is filled into the slots thereby forming the first EMI shielding blocks ~~thereof~~.

14. (currently amended): The compound material as claimed in claim 13, wherein the first EMI shielding blocks are alternately and separately arranged in the first heat conductive sub-layer.

15. (currently amended): The compound material as claimed in claim 14, wherein the first EMI shielding blocks are integrated with the first heat conductive sub-layer by planography printing or insert-molding methods.

16. (currently amended): The compound material as claimed in claim 15, ~~wherein further comprises~~ comprising a second EMI shielding layer overlapped on ~~the side of the~~ the first heat conductive layer ~~which is and~~ opposite to ~~said the~~ the first EMI shielding layer.

17. (currently amended): The compound material as claimed in claim 16, wherein the second EMI shielding layer ~~also has a~~ second high heat conductive sub-layer forming a plurality of second slots therein and a plurality of second EMI shielding blocks which is formed by filling EMI shielding material into the second slots of the second heat conductive sub-layer.

18. (currently amended): The compound material as claimed in claim 17, wherein the second EMI shielding blocks of the second EMI shielding layer are alternately and separately arranged in ~~a similar as the EMI shielding blocks of said EMI shielding layer~~ second heat conductive sub-layer.

19. (currently amended): The compound material as claimed in claim 18, wherein the second EMI shielding blocks of the second EMI shielding layer are staggered from the first EMI shielding blocks of ~~said~~ first EMI shielding layer in the overlapped or vertical direction thereof.

20. (currently amended): The compound material as claimed in claim ~~12~~ 17, wherein the material of the first and second EMI shielding blocks of ~~said the first and second~~ EMI shielding ~~layer-layers and the second EMI shielding layer~~ is a suitable electromagnetic wave absorbing material.

21. (currently amended): The compound material as claimed in claim 20, wherein the heat conductive ~~layer-layers~~ and the heat conductive ~~sub-layer sub-layers~~ are formed by infiltrating  $\text{Al}_2\text{O}_3$  powder into a suitable thermoplastic base material.

22. - 24. (canceled).